

## REMARKS

Claims 1 - 5, 7, 13, 14, 15 - 18, 37 and 40 are pending in the Application, and claims 8 - 12, 19 - 36, 38 and 39 are cancelled.

## ALLOWABLE SUBJECT MATTER

The present Office Action alleges that the previously indicated allowable subject matter for Claims 15 which was included in independent Claim 13 per the indication of the previous Office Action is now withdrawn in light of newly discovered references to Han et al. and Magdo. Applicants respectfully assert the present Office Action rejects Claim 13, 14, 16 - 18 and 36 - 40 with a 102 rejection and does not indicate Claim 13 is rejected in light of the newly discovered references. Applicants respectfully request reinstatement of the allowable subject matter for Claim 13.

## DRAWINGS

Applicants have amended Claim 13 to remove "package substrate includes a conductive trace .... within said package substrate and along said

conductive trace" and changed "said signal redistribution layer" to "a signal redistribution layer". Applicants have cancelled Claim 38.

#### 112 REJECTIONS

Applicants have amended Claim 13 to remove "package substrate includes a conductive trace .... within said package substrate and along said conductive trace" and changed "said signal redistribution layer" to "a signal redistribution layer". Applicants have cancelled Claim 38.

#### 102 REJECTIONS

The present Office Action indicates Claims 13, 14, and 16 - 18 are rejected under 35 U.S.C. 102 (b) as being anticipated by Motika et al. (US 5,807,763).

Applicants respectfully assert that the present invention is neither shown nor suggested by the Motika et al. reference.

To the extent the present Office Action indicated that the claim includes functional and intended use limitations that are not given patentable weight,

Applicants have amended the claims to include "means" language in and effort

to expedite resolution of the present Application. Applicants respectfully assert that the Motika et al. reference is not directed to the present invention as recited in Claim 13. Specifically the present invention, as set forth in independent Claim 13 recites in part:

... a semiconductor die having test probe points accessible  
by said external access point, wherein said semiconductor die is  
electrically coupled to said package substrate ... .

To the extent the Motika et al. reference may mention pads or bumps 140 may be provided over the passivation layer at the cavities, or the cavities may be made larger to expose pads of the wiring layers [Col. 6 lines19 -22], Applicants respectfully assert the Motika et al. reference does not teach a test signal redistribution trace is disposed such that multiple test signals are ***accessible at varying degrees*** of electronic component granularity within the die and ***along*** the test signal redistribution layer trace. Applicants respectfully assert that no matter where a test point is moved along the redistribution trace it is limited to the same granularity as the pad 40 and thus the same ***unvarying*** granularity of electronic component access the corresponding bonding pad has to the internal circuitry.

Applicants respectfully assert Claims 14 and 16 - 18 are allowable as depending from allowable independent Claim 13.

### 103 REJECTIONS

The present Office Action indicates Claims 1 - 5 and 7 are rejected under 35 U.S.C. 103 (a) as being unpatentable over Han et al. (U.S. 6,429,532) in view of Magado (U.S. 5,262,719). Applicants respectfully assert that the present invention is neither shown nor suggested by the cited references, alone or together.

To the extent the present Office Action indicated that the claim includes functional and intended use limitations that are not given patentable weight, Applicants have amended the claims to include "means" language in an effort to expedite resolution of the present Application. With respect to Claim 1, the present invention, as set forth in independent Claim 1 recites in part:

... wherein said test signal redistribution layer trace is routed in a spiral pattern included in a redistribution layer and said test signal redistribution layer trace is disposed such that multiple test signals are accessible at varying degrees of electronic component

granularity within said die and along said test signal

redistribution layer trace ... .

To the extent the Han et al. reference may mention a redistribution layer

212 is formed between the bonding pad 202 and the bump 204 and one

of **portion 212a** is used as **testing pad** [Col. 2 lines 45 - 55, Figure 2] and

testing pads **404a** are formed **beside** bumps 402 [Col. 2 lines 58-59,

Figure 4], Applicants respectfully assert the Han et al. reference does not

teach test signal redistribution layer trace is disposed such that multiple

test signals are accessible at **varying degrees** of electronic component

granularity within the die.

The present Office Action acknowledges the Han et al. reference does not  
each the test signal redistribution layer trace routed in a spiral pattern.

Applicants respectfully assert the Magdo reference does not overcome these and  
other short comings of the Han et al. reference.

Applicants respectfully assert Claims 1 - 6 and 7 are allowable as  
depending from an allowable independent Claim 1.

The present Office Action indicates Claims 36 - 40 are rejected under 35 U.S.C. 103 (a) as being unpatentable over Motika in view of Magado (U.S. 5,262,719). Applicants respectfully assert that the present invention is neither shown nor suggested by the cited references, alone or together.

Applicants have Cancelled Claims 36, 38 and 39.

Applicants have amended Claims 37 and 40 to depend from Claim 13. As indicated above, to the extent the Motika et al. reference may mention pads or bumps 140 may be provided over the passivation layer at the cavities, or the cavities may be made larger to expose pads of the wiring layers [Col. 6 lines 19 - 22], Applicants respectfully assert the Motika et al. reference does not teach a test signal redistribution trace is disposed such that multiple test signals are ***accessible at varying degrees*** of electronic component granularity within the die and ***along*** the test signal redistribution layer trace.

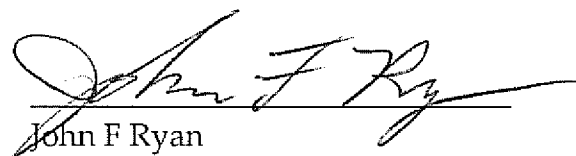
The present Office Action acknowledges the Motika reference does not teach the test signal redistribution layer trace routed in a spiral pattern. Applicants respectfully assert the Magdo reference does not overcome these and other shortcomings of the Han et al. reference.

## CONCLUSION

In light of the above-listed amendments and remarks, Applicants respectfully request allowance of the remaining Claims. The examiner is urged to contact Applicants' undersigned representative if the Examiner believes such action would expedite resolution of the present Application. Applicants believe no additional extension of time is necessary beyond the 2 Month extension of time under previously submitted. If an additional extension of time is required, please consider this a petition therefore. Please charge and additional fees or apply any credits to our PTO deposit account number: 50-4160.

Respectfully submitted,  
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